While at many other companies activities wound down during the holiday period, at RoodMicrotec things are busier than ever as we prepare for the second half of 2011. We will not be closing for the holidays.

As we pointed out in our press release of 7 July of this year, our test engineering activities in particular showed a sharp sales increase. We achieved a sales increase of no less than 46.4% compared to the first half of 2010. To avoid bottlenecks in the second half, we are currently looking for ambitious engineers to reinforce our test engineering departments in both Stuttgart and Nördlingen. For details, please refer to our website RoodMicrotec.com. We ask people who are looking for a challenging job to take a look on our website, and wish everyone a pleasant summer holiday.

Vacancies for engineers

Günter Kohm (57) joined RoodMicrotec’s Failure & Technology Analysis business unit in February this year. He has many years experience in the semiconductor industry, having started his career in 1977 with IBM, where he was responsible for functional tests of bipolar products. Over the past three years, he worked for NXP Hamburg in the field of electrical and physical failure analysis (FA).

Günter’s expertise is in the area of electrical failure analysis, which takes testing deep into the application. His experience will be very useful indeed to RoodMicrotec, as it wishes to become more active in this area. ‘In any valid failure analysis, the history of the failing component is first reviewed. This, along with any electrical information, provides the basis for the failure analysis plan. A well thought-out plan is essential for good results and decreases the likelihood of incurring extraneous expenses for the customer.’

Electrical and physical failure analysis is necessary to understand the root cause of the failure and how it can be prevented in the future. In general, the results of the various techniques will collectively point to the real failure. Electrical failure analysis is one of the techniques used for this. Electrical failures can either be functional or parametric. Functional failure refers to the inability of a device to perform its intended function. Parametric failures may be present while the device is still functional (e.g. leakage current, IDDQ). They are also an indicator of a problem in the device influencing the long term reliability.

RoodMicrotec gains experience in physical and electrical failure analysis
Adieu, Manfred

We were deeply saddened by the sudden and unexpected death of Manfred Schilling on 16 July 2011.

Manfred successfully represented RoodMicrotec and its services for over five years. He was a valuable, highly competent and well-known contact person within the European electronic industry for several decades.

Manfred, we will miss you, we will miss your helpfulness, your optimism and your open and charming manner. We will always remember you in our thoughts and hearts. Our sympathy goes out to your wife and your family at this difficult time.

Philip Nijenhuis, CEO, on behalf of the employees and the supervisory board of RoodMicrotec.

In this newsletter we are happy to introduce our new Supply Chain Management team consisting of Alexander Fritsch, Hermann Schmid, Michael Denu and Alexander Scheitza.

Alexander Fritsch is charged with commercial and operational matters. His responsibilities include revenue planning and sales forecasts, acting as customer contact for delivery contracts & delivery plans, wafer procurement, project calculations and monitoring of production and logistics processes.

Technical specialists Hermann Schmid and Michael Denu provide technical clarification of new supplier inquiries, carry out feasibility studies for customer projects and customer support in technical matters, draw up and coordinate technical document production and clarify production documents with customers and suppliers. They also deal with project set-up in the ERP system and production flow and providing test data for SCM clients.

Alexander Scheitza is responsible for financial matters, including budget planning, drawing up profit and loss accounts, project calculations and personnel management.

The team are very excited about how things are progressing within Supply Chain Management. Over the past few months especially there was an increase of the number of (promising) applications. The current trend appears to be an increased demand for chip-on-board.

Chip-on-board (COB) has reached the stage where considerable savings in space and cost are achievable. COB was first used in applications such as digital clocks and watches where a single chip per board is used. Since then its use has spread; it is now widely used in for example video cameras, pocket calculators, telephone cards and smart cards.

In the business unit Supply Chain Management RoodMicrotec provides all services from the beginning of the manufacturing process (design with partners) through to delivery to customers including wafer test, assembly with partners, final test, qualification, failure analysis and logistics. RoodMicrotec has the capacity to manage the complete process (flow), but can also provide all individual process steps separately.

During the LED symposium Reinhard Pusch will give a presentation with the following highlights:

- Relevant LED parameters and related datasheet figures
- Methods to evaluate datasheet parameters
- Qualification schemes to reach the reliability targets
- Selection process – practical examples and experiences

More details see http://www.led-professional-symposium.com